

**IN THE CLAIMS:**

Please rewrite Claims 31 and 32 as new Claims 37 and 38, as follows:

~~31, 32~~ 37. A method of forming a plurality of wiring lines of conductive material on a board to form a printed circuit board, comprising:

- (a) forming said plurality of wiring lines, having first and second portions, and a uniform thickness on the board; and
- (b) etching a first of said plurality of wiring lines, such that the first portion is thinner in height than the second portion.

~~33, 34~~ 38. The method as claimed in Claim 37, wherein a second of said plurality of wiring lines is provided, spaced from said first wiring line having said first and second portions, the second wiring line having third and fourth portions, and etching the second wiring line such that the third portion is thinner in height than the fourth portion.